



Part Number : 736560001

Series Number : 73656

Product Category : Backplane Connectors

Product Description : HDM Board-to-Board Backplane Power Module, Vertical, SMC, Power Receptacle, 3 Circuits

Status : Active

Documents & Resources

Drawings

Drawing 736560001_sd.pdf

Packaging Design Drawing PK-70873-0819-001.pdf

3D Models and Design Files

3D Model 736560001_stp.zip


Specifications

Application Specification AS-73656-1998-001.pdf

Product Specification PS-73670-9999-001.pdf

Product Environment Compliance

Compliance

GADSL/IMDS	Compliant with Exemption 44; 34; 33
China RoHS	
EU ELV	Not Relevant
Low-Halogen Status	Low-Halogen per IEC 61249-2-21
REACH SVHC	Not Contained per D(2023)8585-DC (23 Jan 2024)
EU RoHS	Compliant per EU 2015/863

Multiple Part Product Compliance Statements

- Eu RoHS
- REACH SVHC
- Low-Halogen

Multiple Part Industry Compliance Documents

- IPC 1752A Class C
- IPC 1752A Class D
- Molex Product Compliance Declaration

- IEC-62474
- chemSHERPA (xml)

EU RoHS Certificate of Compliance

Part Details

General

Status	Active
Category	Backplane Connectors
Series	73656
Description	HDM Board-to-Board Backplane Power Module, Vertical, SMC, Power Receptacle, 3 Circuits
Application	Backplane
Comments	Midplane Power Module, Molex Series 73659
Component Type	Power Header
Product Family	HDM Backplane Connector System
Product Name	HDM
UPC	800755024777

Agency

CSA	LR19980
UL	E29179

Electrical

Current - Maximum per Contact	15.0A
Data Rate	1.0 Gbps
Shielded	No
Voltage - Maximum	500V AC

Physical

Circuits (Loaded)	3
Circuits (maximum)	3
Color - Resin	Black
Durability (mating cycles max)	250
First Mate / Last Break	No

Flammability	94V-0
Guide to Mating Part	No
Keying to Mating Part	None
Material - Metal	Beryllium Copper
Material - Plating Mating	Gold
Material - Plating Termination	Tin-Lead
Material - Resin	High Temperature Thermoplastic
Net Weight	1.700/g
Number of Columns	1
Number of Pairs	Open Pin Field
Number of Rows	3
Orientation	Vertical
Packaging Type	Tube
PC Tail Length	3.50mm
PCB Locator	No
PCB Retention	Yes
PCB Thickness - Recommended	2.50mm
Pitch - Mating Interface	2.00mm
Pitch - Termination Interface	2.00mm
Plating min - Mating	0.762μm
Plating min - Termination	0.889μm
Polarized to PCB	Yes
Stackable	No
Temperature Range - Operating	-55° to +105°C
Termination Interface Style	Through Hole - Compliant Pin

Solder Process Data

Lead-Free Process Capability	N/A
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